DATA SHEET

74LVC162245A; 74LVCH162245A

16-bit transceiver with direction pin; 30 Ω series termination resistors; 5 V tolerant input/output; 3-state

Product specification
Supersedes data of 1998 Feb 17

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Philips Semiconductors

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FEATURES

- 5 V tolerant inputs/outputs for interfacing with 5 V logic
- Wide supply voltage range from 1.2 to 3.6 V
- CMOS low power consumption
- MULTIBYTE™ flow-through standard pin-out architecture
- Low inductance multiple power and ground pins for minimum noise and ground bounce
- Direct interface with TTL levels
- Inputs accept voltages up to 5.5 V
- Integrated 30 Ω termination resistors
- High-impedance when V_{CC} = 0 V
- All data inputs have bushold (74LVCH162245A only)
- Complies with JEDEC standard no. 8-1A
- ESD protection:
  HBM EIA/JESD22-A114-A exceeds 2000 V
  MM EIA/JESD22-A115-A exceeds 200 V.
- Specified from –40 to +85 °C and –40 to +125 °C.

DESCRIPTION

The 74LVC(H)162245A is a high-performance, low-power, low-voltage, Si-gate CMOS device, superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3 or 5 V devices. In 3-state operation, outputs can handle 5 V. These features allow the use of these devices as translators in a mixed 3.3 and 5 V environment.

The 74LVC(H)162245A is a 16-bit transceiver featuring non-inverting 3-state bus compatible outputs in both send and receive directions.

The 74LVC(H)162245A features two output enable ($n\overline{OE}$) inputs for easy cascading and two send/receive (nDIR) inputs for direction control. $n\overline{OE}$ controls the outputs so that the buses are effectively isolated. This device can be used as two 8-bit transceivers or one 16-bit transceiver.

The 74LVCH162245A bushold data inputs eliminates the need for external pull-up resistors to hold unused inputs.

The 74LVC(H)162245A is designed with 30 Ω series termination resistors in both HIGH and LOW output stages to reduce line noise.

QUICK REFERENCE DATA

GND = 0 V; T_{amb} = 25 °C; $t_r = t_f \leq 2.5$ ns.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t_{PHL}/t_{PLH}	propagation delay nAn to nBn; nBn to nAn	C_L = 50 pF; V_{CC} = 3.3 V	3.3	ns
C_I	input capacitance		5.0	pF
$C_{I/O}$	input/output capacitance		10	pF
C_{PD}	power dissipation capacitance	V_{CC} = 3.3 V; notes 1 and 2	28	pF

Note

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
   $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
   f_i = input frequency in MHz;
   f_o = output frequency in MHz;
   C_L = output load capacitance in pF;
   V_{CC} = supply voltage in Volts;
   N = total load switching outputs;
   $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.
2. The condition is V_I = GND to V_{CC}.

FUNCTION TABLE

See note 1.

INPUT		OUTPUT	
$n\overline{OE}$	nDIR	nAn	nBn
L	L	A = B	inputs
L	H	inputs	B = A
H	X	Z	Z

Note

1. H = HIGH voltage level;
   L = LOW voltage level;
   X = don't care;
   Z = high-impedance OFF-state.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE				
	TEMPERATURE RANGE	PINS	PACKAGE	MATERIAL	CODE
74LVC162245ADL	–40 to +125 °C	48	SSOP48	plastic	SOT370-1
74LVCH162245ADL	–40 to +125 °C	48	SSOP48	plastic	SOT370-1
74LVC162245ADGG	–40 to +125 °C	48	TSSOP48	plastic	SOT362-1
74LVCH162245ADGG	–40 to +125 °C	48	TSSOP48	plastic	SOT362-1

PINNING

SYMBOL	PIN	DESCRIPTION
1DIR	1	direction control input
n.c.	–	not connected
1B0	2	data input/output
1B1	3	data input/output
GND	4, 10, 15, 21, 28, 34, 39, 45	ground (0 V)
1B2	5	data input/output
1B3	6	data input/output
V_{CC}	7, 18, 31, 42	supply voltage
1B4	8	data input/output
1B5	9	data input/output
1B6	11	data input/output
1B7	12	data input/output
2B0	13	data input/output
2B1	14	data input/output
2B2	16	data input/output
2B3	17	data input/output
2B4	19	data input/output
2B5	20	data input/output
2B6	22	data input/output
2B7	23	data input/output
2DIR	24	direction control input
$2\overline{OE}$	25	output enable input (active LOW)
2A7	26	data input/output
2A6	27	data input/output
2A5	29	data input/output
2A4	30	data input/output
2A3	32	data input/output
2A2	33	data input/output
2A1	35	data input/output
2A0	36	data input/output
1A7	37	data input/output
1A6	38	data input/output
1A5	40	data input/output
1A4	41	data input/output
1A3	43	data input/output
1A2	44	data input/output
1A1	46	data input/output
1A0	47	data input/output
$1\overline{OE}$	48	output enable input (active LOW)

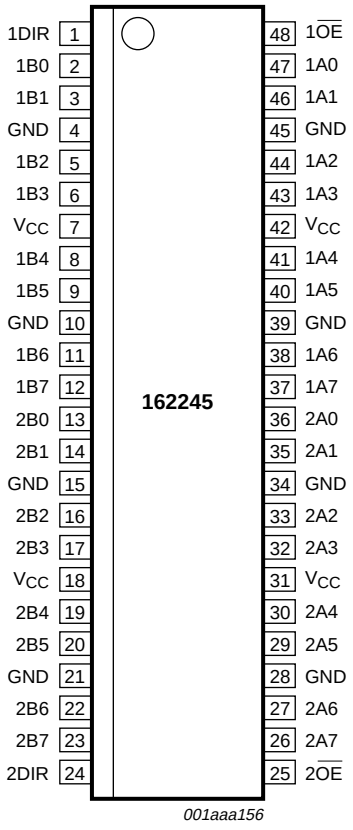


Fig.1 Pin configuration SSOP48 and TSSOP48.

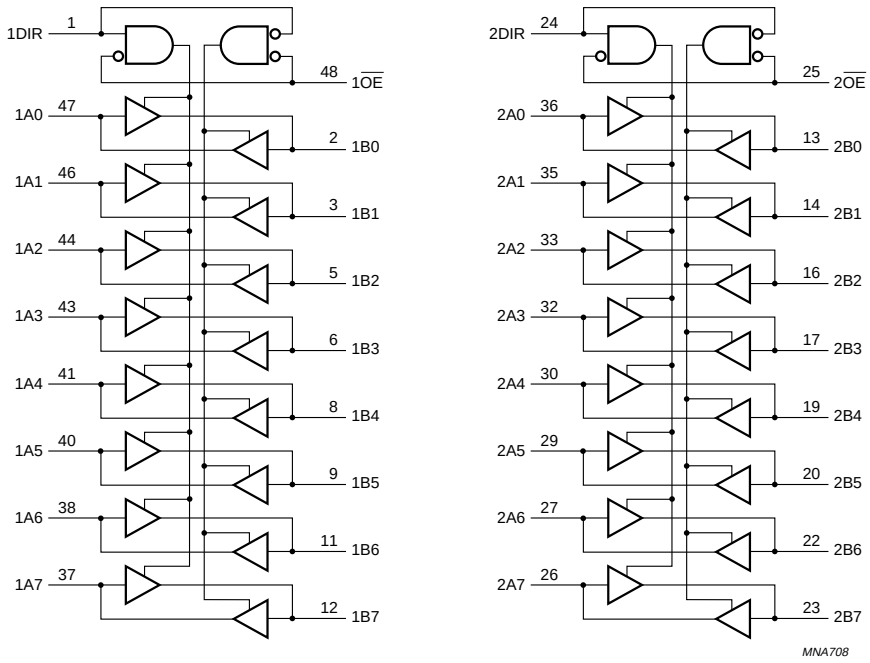


Fig.2 Logic symbol.

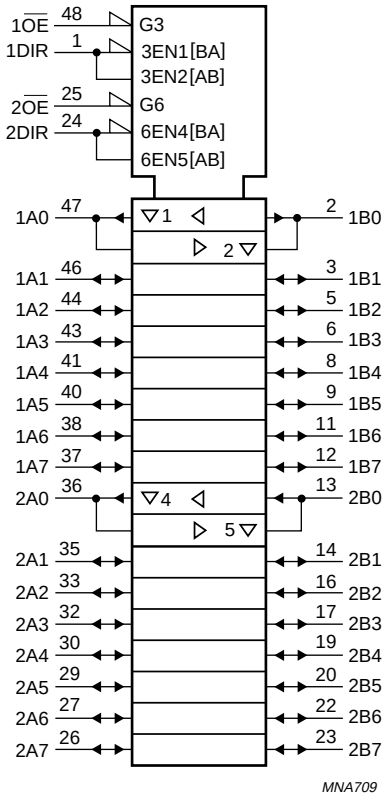


Fig.3 Logic symbol (IEEE/IEC).

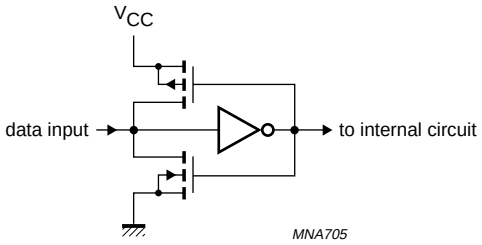


Fig.4 Bushold circuit.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CC}	supply voltage	for maximum speed performance	2.7	3.6	V
		for low voltage applications	1.2	3.6	V
V_I	input voltage		0	5.5	V
V_O	output voltage	output HIGH or LOW state	0	V_{CC}	V
		output 3-state	0	5.5	V
T_{amb}	ambient temperature	in free air	–40	+125	°C
t_r, t_f	input rise and fall times	V_{CC} = 1.2 to 2.7 V	0	20	ns/V
		V_{CC} = 2.7 to 3.6 V	0	10	ns/V

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CC}	supply voltage		–0.5	+6.5	V
I_{IK}	input diode current	$V_I < 0$	–	–50	mA
V_I	input voltage	note 1	–0.5	+6.5	V
I_{OK}	output diode current	$V_O > V_{CC}$ or $V_O < 0$	–	±50	mA
V_O	output voltage	output HIGH or LOW state; note 1	–0.5	V_{CC} + 0.5	V
		output 3-state; note 1	–0.5	+6.5	V
I_O	output source or sink current	V_O = 0 to V_{CC}	–	±50	mA
I_{CC}, I_{GND}	V_{CC} or GND current		–	±100	mA
T_{stg}	storage temperature		–65	+150	°C
P_{tot}	power dissipation	T_{amb} = –40 to +125 °C; note 2	–	500	mW

Notes

1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. Above 60 °C the value of P_{tot} derates linearly with 5.5 mW/K.

DC CHARACTERISTICS

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.(1)	MAX.	UNIT
		OTHER	V_{CC} (V)				
T_{amb} = −40 to +85 °C							
V_{IH}	HIGH-level input voltage		1.2	V_{CC}	–	–	V
			2.7 to 3.6	2.0	–	–	V
V_{IL}	LOW-level input voltage		1.2	–	–	GND	V
			2.7 to 3.6	–	–	0.8	V
V_{OH}	HIGH-level output voltage	V_I = V_{IH} or V_{IL}					
		I_O = –100 μA	2.7 to 3.6	V_{CC} – 0.2	V_{CC}	–	V
		I_O = –6 mA	2.7	V_{CC} – 0.5	–	–	V
		I_O = –12 mA	3.0	V_{CC} – 0.8	–	–	V
V_{OL}	LOW-level output voltage	V_I = V_{IH} or V_{IL}					
		I_O = 100 μA	2.7 to 3.6	–	0	0.20	V
		I_O = 6 mA	2.7	–	–	0.40	V
		I_O = 12 mA	3.0	–	–	0.55	V
I_{LI}	input leakage current	V_I = 5.5 V or GND; note 2	3.6	–	±0.1	±5	μA
I_{OZ}	3-state output OFF-state current	V_I = V_{IH} or V_{IL}; V_O = 5.5 V or GND; notes 2 and 3	3.6	–	±0.1	±5	μA
I_{off}	power-off leakage supply current	V_I or V_O = 5.5 V	0.0	–	±0.1	±10	μA
I_{CC}	quiescent supply current	V_I = V_{CC} or GND; I_O = 0	3.6	–	0.1	20	μA
ΔI_{CC}	additional quiescent supply current per input pin	V_I = V_{CC} – 0.6 V; I_O = 0	2.7 to 3.6	–	5	500	μA
I_{BHL}	bushold LOW sustaining current	V_I = 0.8 V; notes 4 and 5	3.0	75	–	–	μA
I_{BHH}	bushold HIGH sustaining current	V_I = 2.0 V; notes 4 and 5	3.0	–75	–	–	μA
I_{BHLO}	bushold LOW overdrive current	notes 4 and 6	3.6	500	–	–	μA
I_{BHHO}	bushold HIGH overdrive current	notes 4 and 6	3.6	–500	–	–	μA

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.(1)	MAX.	UNIT
		OTHER	V_{CC} (V)				
T_{amb} = −40 to +125 °C							
V_{IH}	HIGH-level input voltage		1.2	V_{CC}	–	–	V
			2.7 to 3.6	2.0	–	–	V
V_{IL}	LOW-level input voltage		1.2	–	–	GND	V
			2.7 to 3.6	–	–	0.8	V
V_{OH}	HIGH-level output voltage	V_I = V_{IH} or V_{IL}					
		I_O = –100 μA	2.7 to 3.6	V_{CC} – 0.3	–	–	V
		I_O = –6 mA	2.7	V_{CC} – 0.65	–	–	V
		I_O = –12 mA	3.0	V_{CC} – 1	–	–	V
V_{OL}	LOW-level output voltage	V_I = V_{IH} or V_{IL}					V
		I_O = 100 μA	2.7 to 3.6	–	–	0.3	
		I_O = 6 mA	2.7	–	–	0.6	V
		I_O = 12 mA	3.0	–	–	0.8	V
I_{LI}	input leakage current	V_I = 5.5 V or GND; note 2	3.6	–	–	±20	μA
I_{OZ}	3-state output OFF-state current	V_I = V_{IH} or V_{IL}; V_O = 5.5 V or GND; notes 2 and 3	3.6	–	–	±20	μA
I_{off}	power-off leakage supply current	V_I or V_O = 5.5 V	0.0	–	–	±20	μA
I_{CC}	quiescent supply current	V_I = V_{CC} or GND; I_O = 0	3.6	–	–	80	μA
ΔI_{CC}	additional quiescent supply current per input pin	V_I = V_{CC} – 0.6 V; I_O = 0	2.7 to 3.6	–	–	5000	μA
I_{BHL}	bushold LOW sustaining current	V_I = 0.8 V; notes 4 and 5	3.0	60	–	–	μA
I_{BHH}	bushold HIGH sustaining current	V_I = 2.0 V; notes 4 and 5	3.0	–60	–	–	μA
I_{BHLO}	bushold LOW overdrive current	notes 4 and 6	3.6	500	–	–	μA
I_{BHHO}	bushold HIGH overdrive current	notes 4 and 6	3.6	–500	–	–	μA

Notes

1. All typical values are measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.
2. For bushold parts, the bushold circuit is switched off when $V_I > V_{CC}$ allowing 5.5 V on the input terminal.
3. For I/O ports the parameter I_{OZ} includes the input leakage current.
4. Valid for data inputs of bushold parts (LVCH162245A) only. For data inputs only, control inputs do not have a bushold circuit.
5. The specified sustaining current at the data input holds the input below the specified V_I level.
6. The specified overdrive current at the data input forces the data input to the opposite logic input state.

AC CHARACTERISTICS

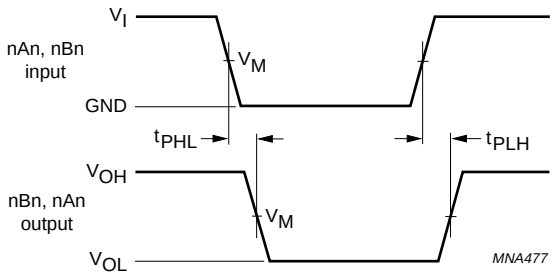
GND = 0 V; $t_r = t_f \leq 2.5$ ns.

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.(1)	MAX.	UNIT
		WAVEFORMS	V_{CC} (V)				
T_{amb} = −40 to +85 °C							
t_{PHL}/t_{PLH}	propagation delay nAn to nBn; nBn to nAn	see Figs 5 and 7	1.2	–	12	–	ns
			2.7	1.0	4.2	6.7	ns
			3.0 to 3.6	1.0	3.3(2)	5.7	ns
t_{PZH}/t_{PZL}	3-state output enable time n$\overline{OE}$ to nAn; n$\overline{OE}$ to nBn	see Figs 6 and 7	1.2	–	18	–	ns
			2.7	1.5	5.1	8.5	ns
			3.0 to 3.6	1.0	3.4(2)	7.5	ns
t_{PHZ}/t_{PLZ}	3-state output disable time n$\overline{OE}$ to nAn; n$\overline{OE}$ to nBn	see Figs 6 and 7	1.2	–	10	–	ns
			2.7	1.5	3.5	7.5	ns
			3.0 to 3.6	1.5	3.3(2)	6.5	ns
T_{amb} = −40 to +125 °C							
t_{PHL}/t_{PLH}	propagation delay nAn to nBn; nBn to nAn	see Figs 5 and 7	1.2	–	–	–	ns
			2.7	1.0	–	8.5	ns
			3.0 to 3.6	1.0	–	9.5	ns
t_{PZH}/t_{PZL}	3-state output enable time n$\overline{OE}$ to nAn; n$\overline{OE}$ to nBn	see Figs 6 and 7	1.2	–	–	–	ns
			2.7	1.5	–	7.5	ns
			3.0 to 3.6	1.0	–	9.5	ns
t_{PHZ}/t_{PLZ}	3-state output disable time n$\overline{OE}$ to nAn; n$\overline{OE}$ to nBn	see Figs 6 and 7	1.2	–	–	–	ns
			2.7	1.5	–	11.0	ns
			3.0 to 3.6	1.5	–	8.5	ns

Notes

1. All typical values are measured at T_{amb} = 25 °C.
2. These typical values are measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.

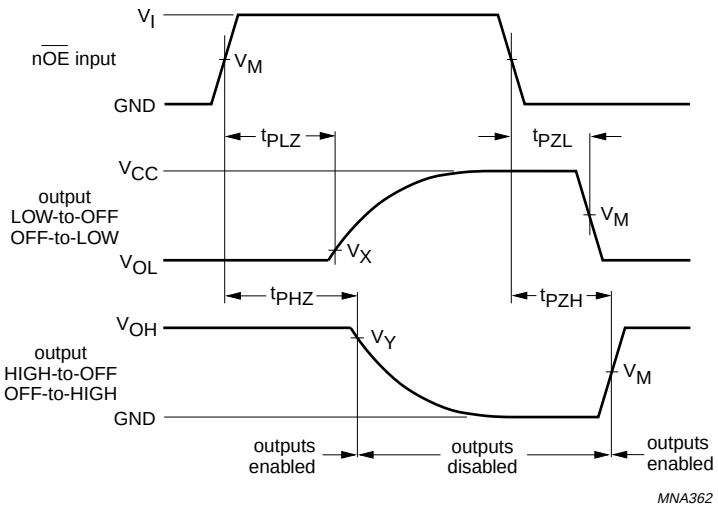
AC WAVEFORMS



V_{CC}	V_M	INPUT	
		V_I	$t_r = t_f$
1.2 V	$0.5 \times V_{CC}$	V_{CC}	≤ 2.5 ns
2.7 V	1.5 V	2.7 V	≤ 2.5 ns
3.0 to 3.6 V	1.5 V	2.7 V	≤ 2.5 ns

V_{OL} and V_{OH} are typical output voltage drop that occur with the output load.

Fig.5 The input (nAn, nBn) to outputs (nBn, nAn) propagation delays.

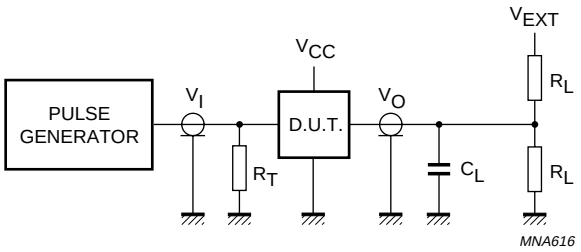


V_{CC}	V_M	INPUT	
		V_I	$t_r = t_f$
1.2 V	$0.5 \times V_{CC}$	V_{CC}	≤ 2.5 ns
2.7 V	1.5 V	2.7 V	≤ 2.5 ns
3.0 to 3.6 V	1.5 V	2.7 V	≤ 2.5 ns

$V_X = V_{OL} + 0.3$ V at $V_{CC} \geq 2.7$ V;
$V_X = V_{OL} + 0.1$ V at $V_{CC} < 2.7$ V;
$V_Y = V_{OH} - 0.3$ V at $V_{CC} \geq 2.7$ V;
$V_Y = V_{OH} - 0.1$ V at $V_{CC} < 2.7$ V.

V_{OL} and V_{OH} are typical output voltage drop that occur with the output load.

Fig.6 3-state enable and disable times.



V_{CC}	V_I	C_L	R_L	V_{EXT}		
				t_{PLH}/t_{PHL}	t_{PZH}/t_{PHZ}	t_{PZL}/t_{PLZ}
1.2 V	V_{CC}	50 pF	500 Ω(1)	open	GND	$2 \times V_{CC}$
2.7 V	2.7 V	50 pF	500 Ω	open	GND	$2 \times V_{CC}$
3.0 to 3.6 V	2.7 V	50 pF	500 Ω	open	GND	$2 \times V_{CC}$

Note

1. The circuit performs better when R_L = 1000 Ω.

Definitions for test circuits:

R_L = Load resistor.

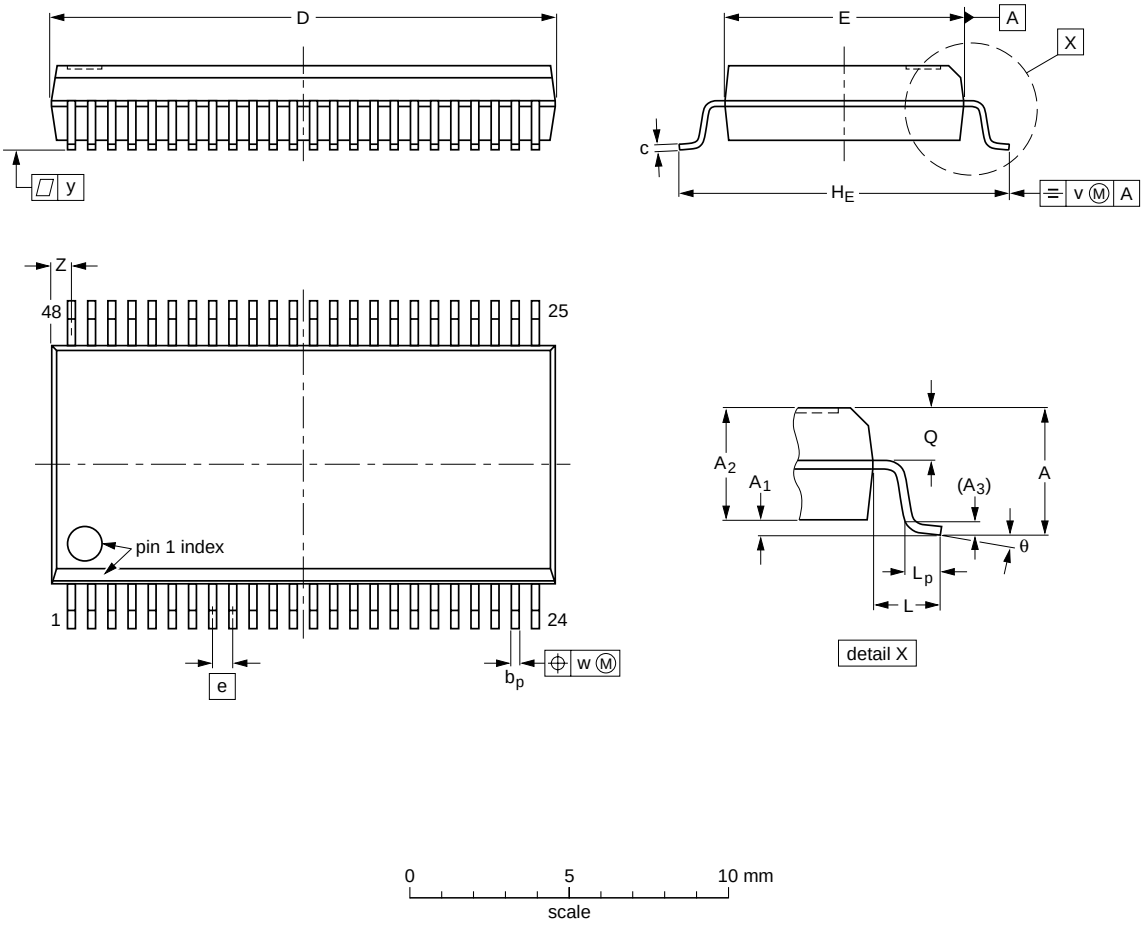
C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to the output impedance Z_o of the pulse generator.

Fig.7 Load circuitry for switching times.

PACKAGE OUTLINES

SSOP48: plastic shrink small outline package; 48 leads; body width 7.5 mm **SOT370-1**



DIMENSIONS (mm are the original dimensions)

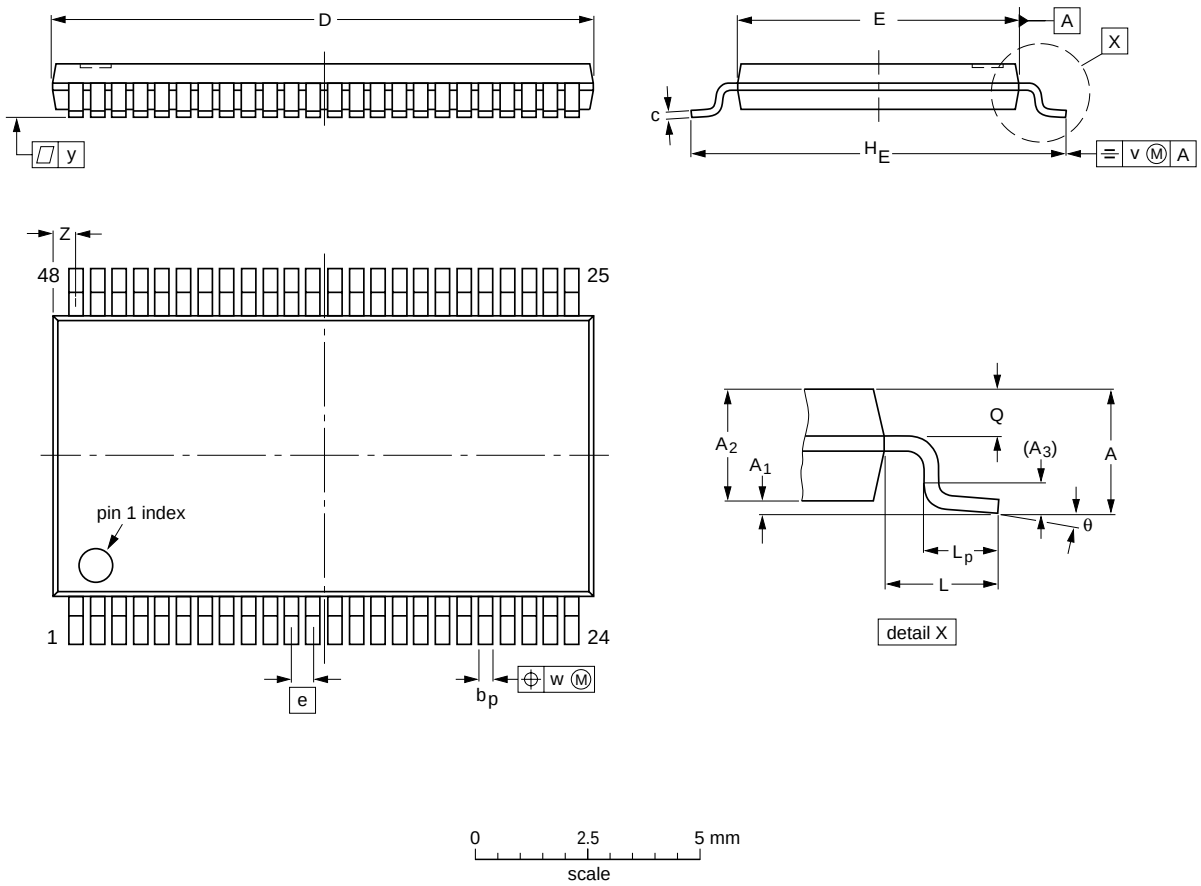
UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	16.00 15.75	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT370-1		MO-118				~~99-12-27~~ 03-02-19

TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1 mm **SOT362-1**



DIMENSIONS (mm are the original dimensions).

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	Z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	**0.2** **0.1**	12.6 12.4	6.2 6.0	0.5	8.3 7.9	1	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.8 0.4	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT362-1		MO-153				~~99-12-27~~ 03-02-19

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS(1)	PRODUCT STATUS(2)(3)	DEFINITION
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DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Contact information

For additional information please visit **http://www.semiconductors.philips.com**. Fax: **+31 40 27 24825**
For sales offices addresses send e-mail to: **sales.addresses@www.semiconductors.philips.com**.

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